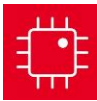




Module 3

Introduction: ARM Cortex M Architecture



Introduction: ARM Cortex M Architecture

Educational Objectives:

REVIEW Cortex M architecture

UNDERSTAND registers, memory, assembly instructions

DEVELOP logic and arithmetic functions in assembly

LEARN how functions work, and where data is stored

DESIGN, BUILD & TEST A COMPONENT

Nonlinear conversion function for an IR distance sensor

Prerequisites (Module 1)

- Running code on the LaunchPad using CCS (Module 1)

Recommended reading materials for students:

- Volume 1 Section 1.7, Chapter 3, and Section 5.3
Embedded Systems: Introduction to the MSP432 Microcontroller
ISBN: 978-1512185676, Jonathan Valvano, copyright (c) 2017

or

- Volume 2 Sections 1.1, 2.1, and 2.5
Embedded Systems: Real-Time Interfacing to the MSP432 Microcontroller, ISBN: 978-1514676585, Jonathan Valvano, copyright (c) 2017

In this class, we will use the TI Launchpad Development Kit with the MSP432 microcontroller, which includes a Cortex-M processor and a suite of input/output devices derived from the MSP430 family of low power microcontrollers.

Architecture is the manner with which the processor, random access memory (RAM), read only memory (ROM), and input/output (I/O) ports are combined to create the microcontroller. See Figure 1.

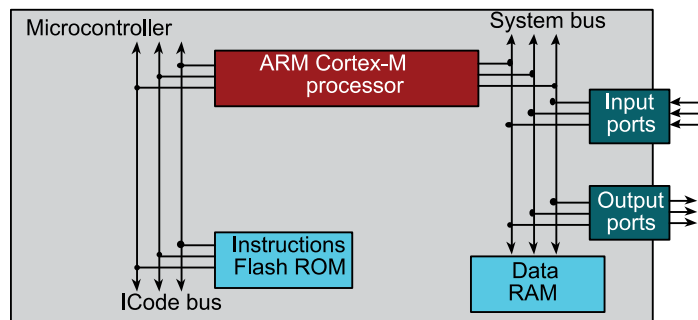


Figure 1. Architecture of an ARM Cortex M microcontroller.

This module serves as a brief introduction to the Cortex M microcontroller. Even though we typically program embedded systems in C, it makes sense to understand a little bit how the microcontroller executes software. Understanding some of these low level details will make it easier to make high level software design decisions. Examples where knowing low-level details make for better high-level decisions include: local versus global variables, numbers versus pointers, numerical overflow during calculations, numerical dropout during divide and right shift operations, integer versus floating point calculations, and interrupts.

There are two reasons we must learn the assembly language of the computer with which we are using. Sometimes, but not often, we wish to optimize our application for maximum execution speed or minimum memory size, and thus writing pieces of our code in assembly language is one approach to such optimizations. The most important reason, however, is that by observing the assembly code generated by the compiler for our C code we can truly understand what our software is doing. Based on this understanding, we can evaluate, debug, and optimize our system. So the goal of this module is not for you to become proficient in assembly language, but rather to learn enough so you can interpret the assembly code generated by the C compiler.

An **assembler** is system software that converts low-level assembly language program (human readable format) into object code (machine readable format). Typically, one line of assembly language creates one machine instruction, and this translation is simple and obvious. Writing in assembly exposes the low-level details of the architecture.

A **linker** builds a single software system by connecting (linking) software components. In CCS, the **build** command performs both assembly and linking. In an embedded system, the **loader** will program object code into flash ROM. We place object code in ROM because ROM retains its information if power is removed and restored. In CCS, the **Debug** command performs a load operation and starts the debugger.

A **debugger** is a set of hardware and software tools we use to verify system is operating correctly. The two important aspects of a good debugger are control and observability.

In the lab associated with this module, you will develop and test an assembly function typical of one the robot might use to perform a numerical calculation. In particular, the function will convert ADC measurements from a sensor into distance to the wall. In developing and debugging this function, you will gather important insights on how the Cortex-M processor executes software.

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